

# 8-BIT MICROCONTROLLER

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#### 1. GENERAL DESCRIPTION

The W78L32 microcontroller supplies a wider frequency range and supply voltages than most 8-bit microcontrollers on the market. It is compatible with the industry standard 80C32 microcontroller series.

The W78L32 contains four 8-bit bidirectional parallel ports, three 16-bit timer/counters and a serial port. These peripherals are supported by a six-source, two-level interrupt capability. There are 256 bytes of RAM, and the device supports ROMless operation for application programs.

The W78L32 microcontroller has two power reduction modes, idle mode and power-down mode, both of which are software selectable. The idle mode turns off the processor clock but allows for continued peripheral operation. The power-down mode stops the crystal oscillator for minimum power consumption. The external clock can be stopped at any time and in any state without affecting the processor.

#### 2. FEATURES

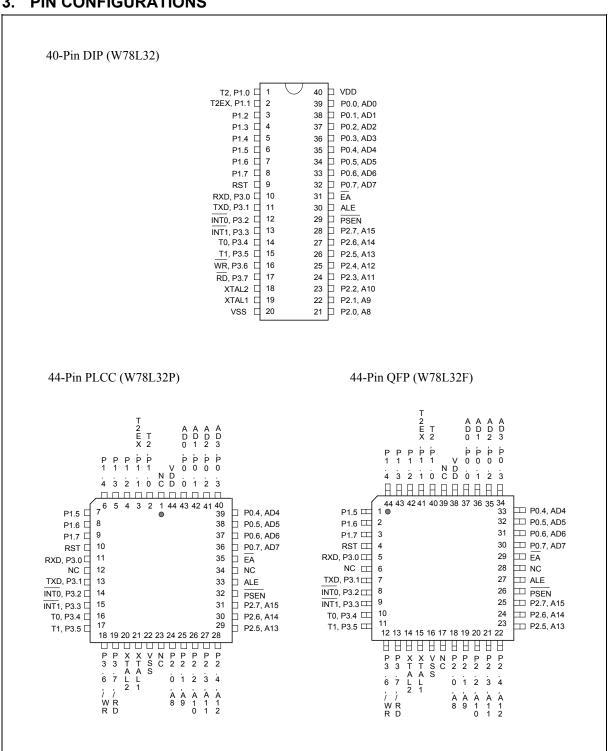
- Fully static design
- Supply voltage of 1.8V to 5.5V
- Low power consumption at full supply voltage
- DC-24 MHz operation
- 256 bytes of on-chip scratchpad RAM
- 64K bytes program memory address space
- 64K bytes data memory address space
- Four 8-bit bidirectional ports
- Three 16-bit timer/counters
- One full duplex serial port
- Boolean processor
- Six-source, two-level interrupt capability
- Built-in power management
- Packages:

DIP 40: W78L32-24PLCC 44: W78L32P-24QFP 44: W78L32F-24

Lead Free (RoHS) DIP 40: W78L032A24DL, W78M032A24DL
 Lead Free (RoHS) PLCC 44: W78L032A24PL, W78M032A24PL
 Lead Free (RoHS) PQFP 44: W78L032A24FL, W78M032A24FL



#### PIN CONFIGURATIONS





#### 4. PIN DESCRIPTION

#### P0.0-P0.7

Port 0, Bits 0 through 7. Port 0 is a bidirectional I/O port. This port also provides a multiplexed low order address/data bus during accesses to external memory.

#### P1.0-P1.7

Port 1, Bits 0 through 7. Port 1 is a bidirectional I/O port with internal pull-ups. Pins P1.0 and P1.1 also serve as T2 (Timer 2 external input) and T2EX (Timer 2 capture/reload trigger), respectively.

#### P2.0-P2.7

Port 2, Bits 0 through 7. Port 2 is a bidirectional I/O port with internal pull-ups. This port also provides the upper address bits for accesses to external memory.

#### P3.0-P3.7

Port 3, Bits 0 through 7. Port 3 is a bidirectional I/O port with internal pull-ups. All bits have alternate functions, which are described below:

PIN	ALTERNATE FUNCTION
P3.0	RXD Serial Receive Data
P3.1	TXD Serial Transmit Data
P3.2	INT0 External Interrupt 0
P3.3	INT1 External Interrupt 1
P3.4	T0 Timer 0 Input
P3.5	T1 Timer 1 Input
P3.6	WR Data Write Strobe
P3.7	RD Data Read Strobe

#### EA

External Address Input, active low. This pin forces the processor to execute out of external ROM. This pin should be kept low for all W78L32 operations.

#### **RST**

Reset Input, active high. This pin resets the processor. It must be kept high for at least two machine cycles in order to be recognized by the processor.

#### **ALE**

Address Latch Enable Output, active high. ALE is used to enable the address latch that separates the address from the data on Port 0. ALE runs at 1/6th of the oscillator frequency. A single ALE pulse is skipped during external data memory accesses. ALE goes to a high state during reset with a weak pull-up.



#### **PSEN**

Program Store Enable Output, active low. PSEN enables the external ROM onto the Port 0 address/data bus during fetch and MOVC operations. PSEN goes to a high state during reset with a weak pull-up.

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#### XTAL1

Crystal 1. This is the crystal oscillator input. This pin may be driven by an external clock.

#### XTAL2

Crystal 2. This is the crystal oscillator output. It is the inversion of XTAL1.

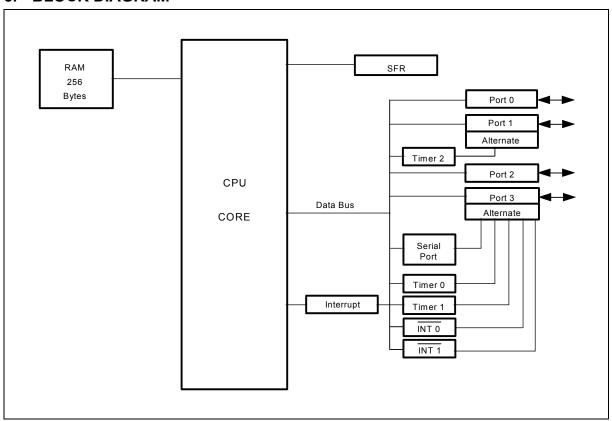
#### Vss, VDD

Power Supplies. These are the chip ground and positive supplies.

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## 5. BLOCK DIAGRAM





#### 6. FUNCTIONAL DESCRIPTION

The W78L32 architecture consists of a core controller surrounded by various registers, four general purpose I/O ports, 256 bytes of RAM, three timer/counters, and a serial port. The processor supports 111 different instruction and references both a 64K program address space and a 64K data storage space.

#### **Timers 0, 1, and 2**

Timers 0, 1, and 2 each consist of two 8-bit data registers. These are called TL0 and TH0 for Timer 0, TL1 and TH1 for Timer 1, and TL2 and TH2 for Timer 2. The TCON and TMOD registers provide control functions for timers 0, 1. The T2CON register provides control functions for Timer 2. RCAP2H and RCAP2L are used as reload/capture registers for Timer 2.

The operations of Timer 0 and Timer 1 are the same as in the W78C31. Timer 2 is a special feature of the W78L32: it is a 16-bit timer/counter that is configured and controlled by the T2CON register. Like Timers 0 and 1, Timer 2 can operate as either an external event counter or as an internal timer, depending on the setting of bit C/T2 in T2CON. Timer 2 has three operating modes: capture, autoreload, and baud rate generator. The clock speed at capture or auto-reload mode is the same as that of Timers 0 and 1.

#### Clock

The W78L32 is designed to be used with either a crystal oscillator or an external clock. Internally, the clock is divided by two before it is used. This makes the W78L32 relatively insensitive to duty cycle variations in the clock.

#### **Crystal Oscillator**

The W78L32 incorporates a built-in crystal oscillator. To make the oscillator work, a crystal must be connected across pins XTAL1 and XTAL2. In addition, a load capacitor must be connected from each pin to ground, and a resistor must also be connected from XTAL1 to XTAL2 to provide a DC bias when the crystal frequency is above 24 MHz.

#### **External Clock**

An external clock should be connected to pin XTAL1. Pin XTAL2 should be left unconnected. The XTAL1 input is a CMOS-type input, as required by the crystal oscillator. As a result, the external clock signal should have an input one level of greater than 3.5 volts when VDD = 5V.

#### **Power Management**

#### **Idle Mode**

The idle mode is entered by setting the IDL bit in the PCON register. In the idle mode, the internal clock to the processor is stopped. The peripherals and the interrupt logic continue to be clocked. The processor will exit idle mode when either an interrupt or a reset occurs.

#### **Power-down Mode**

When the PD bit of the PCON register is set, the processor enters the power-down mode. In this mode all of the clocks, including the oscillator are stopped. The only way to exit power-down mode is by a reset.

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#### Reset

The external RESET signal is sampled at S5P2. To take effect, it must be held high for at least two machine cycles while the oscillator is running. An internal trigger circuit in the reset line is used to deglitch the reset line when the W78L32 is used with an external RC network. The reset logic also has a special glitch removal circuit that ignores glitches on the reset line. During reset, the ports are initialized to FFH, the stack pointer to 07H, PCON (with the exception of bit 4) to 00H, and all of the other SFR registers except SBUF to 00H. SBUF is not reset.

#### 7. ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
DC Power Supply	Vcc-Vss	-0.3	+7.0	V
Input Voltage	VIN	Vss -0.3	Vcc +0.3	V
Operating Temperature	TA	0	70	°C
Storage Temperature	Тѕт	-55	+150	°C

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

#### 8. DC CHARACTERISTICS

(VDD-Vss = 5V  $\pm$ 10%, TA = 25°C, Fosc = 20 MHz, unless otherwise specified.)

PARAMETER	SYM.	PECIFIC	CATION	UNIT	TEST CONDITIONS
PANAMETER	MIN. MAX.		0111	TEST CONDITIONS	
Operating Voltage	VDD	1.8	5.5	V	
Operating Current	IDD	ı	20	mA	No load, VDD = 5.5V, 20 MHz
		-	3	mA	No load, VDD = 2.0V, 16 MHz
Idle Current	IDLE	ı	6	mA	V <sub>DD</sub> = 5.5V, Fosc = 20 MHz
		-	1.5	mA	V <sub>DD</sub> = 2.0V, Fosc =16 MHz
Power Down Current	IPWDN	-	50	μΑ	VDD = 5.5V, Fosc = 20 MHz
		-	20	μΑ	VDD = 2.0V, Fosc = 16 MHz
Input Current	linia	50	.10	^	VDD = 5.5V
P1, P2, P3	lin1	-50	+10	μΑ	VIN = 0V or VDD
Input Current	lin2	-10	+300	^	VDD = 5.5V
RST	IIINZ	-10	1300	μΑ	0 < VIN < VDD
Input Leakage Current	luz	10	. 10	۸	VDD = 5.5V
P0, <del>EA</del>	ILK	-10	+10	μΑ	0V < VIN < VDD
Logic 1 to 0 Transition					VDD = 5.5V
Current	ITL [*4]	-500	-	μΑ	VIN = 2.0V
P1, P2, P3					2.50



#### DC Characteristics, continued

PARAMETER	SYM.	PECIFICATION		UNIT	TEST CONDITIONS
FAILAMETER	31 W.	MIN.	MAX.	ONIT	TEST CONDITIONS
Input Low Voltage	VIL1	0	0.8	V	VDD = 4.5V
P0, P1, P2, P3, <del>EA</del>		0	0.5	V	VDD = 2.0V
Input Low Voltage	VIL2	0	0.8	V	VDD = 4.5V
RST		0	0.3	V	VDD = 2.0V
Input Low Voltage	VIL3	0	0.8	V	VDD = 4.5V
XTAL1 [*4]		0	0.6	V	VDD = 2.0V
Input High Voltage	VIH1	2.4	VDD +0.2	V	VDD = 5.5V
P0, P1, P2, P3, <del>EA</del>		1.4	VDD +0.2	V	V <sub>DD</sub> = 2.0V
Input High Voltage	VIH2	3.5	VDD +0.2	V	VDD = 5.5V
RST		1.7	VDD +0.2	V	VDD = 2.0V
Input High Voltage	VIH3	3.5	VDD +0.2	V	VDD = 5.5V
XTAL1 [*4]		1.6	VDD +0.2	V	VDD = 2.0V
Output Low Voltage	VOL1	ı	0.45	V	$V_{DD} = 4.5V$ , $I_{OL} = +2 \text{ mA}$
P1, P2, P3		-	0.25	V	$V_{DD} = 2.0V, I_{OL} = +1 \text{ mA}$
Output Low Voltage	VOL2	-	0.45	V	VDD = 4.5V, IOL = +4 mA
P0, ALE, PSEN [*3]		-	0.25	V	VDD = 2.0V, $IOL = +2 mA$
Sink Current	Isk1	4	9	mA	VDD = 4.5V, Vin = 0.45V
P1, P2, P3		1.8	5.4	mA	$V_{DD} = 2.0V, Vin = 0.45V$
Sink Current	ISK2	8	16	mA	VDD = 4.5V, $Vin = 0.45V$
P0, ALE, PSEN		4.5	9	mA	$V_{DD} = 2.0V$ , $V_{ID} = 0.45V$
Output High Voltage	Voн1	2.4	-	V	VDD = 4.5V, IOH = -100 μA
P1, P2, P3		1.4	-	V	$V_{DD} = 2.0V$ , $I_{OH} = -8 \mu A$
Output High Voltage	VOH2	2.4	-	V	$V_{DD}$ = 4.5V, IOH = -400 $\mu$ A
P0, ALE, PSEN [*3]		1.4	-	V	VDD = 2.0V, IOH = -200 $\mu$ A
Source Current	ISR1	-100	-250	μА	VDD = 4.5V,Vin = 2.4V
P1, P2, P3		-12	-30	μА	VDD = 2.0V,Vin = 1.4V
Source Current	ISR2	-8	-16	mA	V <sub>DD</sub> = 4.5V,Vin = 2.4V
P0, ALE, PSEN		-1.4	-2.4	mA	VDD = 2.0V,Vin = 1.4V

#### Notes:

<sup>\*1.</sup> RST pin is a Schmitt trigger input.

<sup>\*3.</sup> P0, ALE and /PSEN are tested in the external access mode.

<sup>\*4.</sup> XTAL1 is a CMOS input.

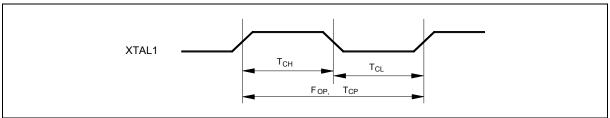
<sup>\*5.</sup> Pins of P1, P2, P3 can source a transition current when they are being externally driven from 1 to 0.



#### 9. AC CHARACTERISTICS

The AC specifications are a function of the particular process used to manufacture the part, the ratings of the I/O buffers, the capacitive load, and the internal routing capacitance. Most of the specifications can be expressed in terms of multiple input clock periods (TcP), and actual parts will usually experience less than a  $\pm 20$  nS variation. The numbers below represent the performance expected from a 0.5 micron CMOS process when using 2 and 4 mA output buffers.

### **Clock Input Waveform**



PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
Operating Speed	Fop	0	-	24	MHz	1
Clock Period	Тср	41.7	-	-	nS	2
Clock High	Тсн	20	-	-	nS	3
Clock Low	TCL	20	-	-	nS	3

#### Notes:

- 1. The clock may be stopped indefinitely in either state.
- 2. The TCP specification is used as a reference in other specifications.
- 3. There are no duty cycle requirements on the XTAL1 input.

#### **Program Fetch Cycle**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
Address Valid to ALE Low	TAAS	1 Tcp-∆	-	-	nS	4
Address Hold after ALE Low	Таан	1 Tcp-∆	-	-	nS	1, 4
ALE Low to PSEN Low	TAPL	1 Tcp-Δ	-	-	nS	4
PSEN Low to Data Valid	TPDA	-	-	2 TCP	nS	2
Data Hold after PSEN High	TPDH	0	-	1 Tcp	nS	3
Data Float after PSEN High	TPDZ	0	-	1 Tcp	nS	
ALE Pulse Width	TALW	2 Tcp-Δ	2 TCP	-	nS	4
PSEN Pulse Width	TPSW	3 ТСР-∆	3 Тср	-	nS	4

#### Notes

- 1. P0.0–P0.7, P2.0–P2.7 remain stable throughout entire memory cycle.
- 2. Memory access time is 3 Tcp.
- 3. Data have been latched internally prior to PSEN going high.
- 4. "\(\Delta\)" (due to buffer driving delay and wire loading) is 20 nS.



## **Data Read Cycle**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
ALE Low to RD Low	TDAR	3 Тср-∆	-	3 ТСР+∆	nS	1, 2
RD Low to Data Valid	TDDA	-	-	4 Tcp	nS	1
Data Hold after RD High	TDDH	0	-	2 Tcp	nS	
Data Float after RD High	TDDZ	0	-	2 Tcp	nS	
RD Pulse Width	TDRD	6 Тср-∆	6 TCP	-	nS	2

#### Notes:

- 1. Data memory access time is 8 Tcp.
- 2. " $\Delta$ " (due to buffer driving delay and wire loading) is 20 nS.

## **Data Write Cycle**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
ALE Low to WR Low	TDAW	3 Тср-∆	-	3 Тср+∆	nS
Data Valid to WR Low	TDAD	1 Тср-∆	-	-	nS
Data Hold from WR High	Towd	1 Тср-∆	-	-	nS
WR Pulse Width	Towr	6 Тср-∆	6 Tcp	-	nS

Note: " $\Delta$ " (due to buffer driving delay and wire loading) is 20 nS.

## **Port Access Cycle**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Port Input Setup to ALE Low	TPDS	1 Tcp	-	-	nS
Port Input Hold from ALE Low	TPDH	0	-	-	nS
Port Output to ALE	TPDA	1 Tcp	-	-	nS

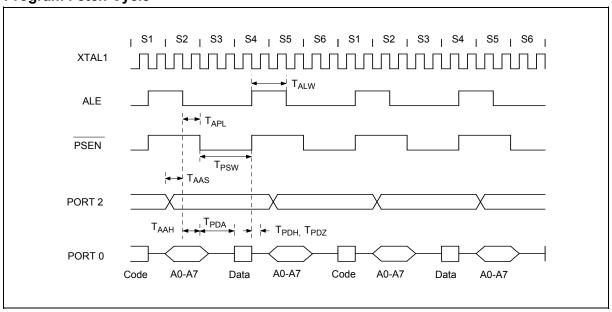
**Note**: Ports are read during S5P2, and output data becomes available at the end of S6P2. The timing data are referenced to ALE, since it provides a convenient reference.

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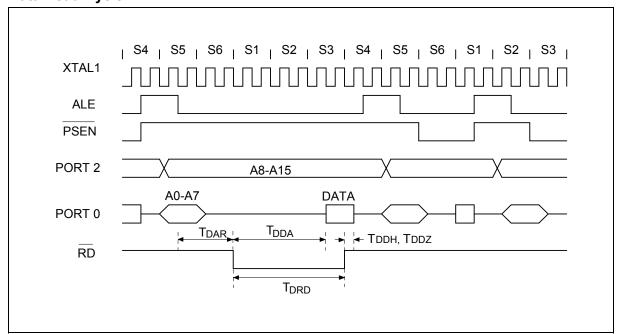


#### 10. TIMING WAVEFORMS

### **Program Fetch Cycle**



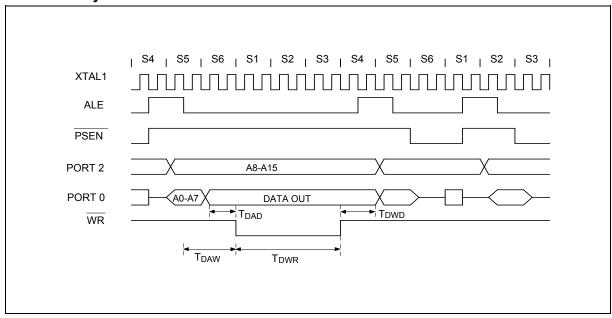
## **Data Read Cycle**



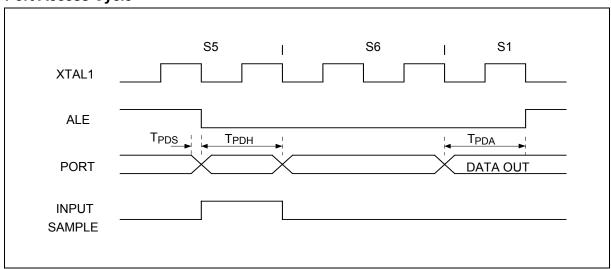


Timing Waveforms, continued

### **Data Write Cycle**



## **Port Access Cycle**





#### 11. TYPICAL APPLICATION CIRCUITS

#### **Using External Program Memory and Crystal**

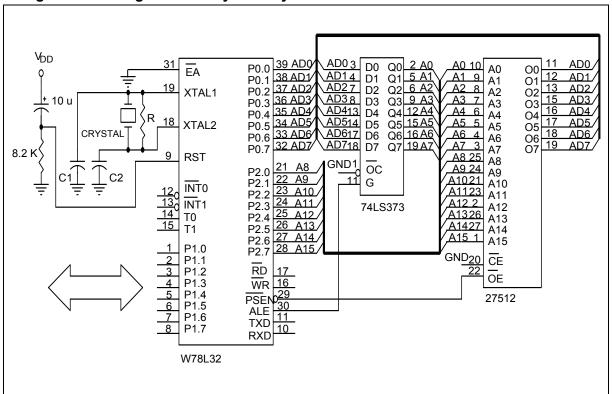


Figure A

CRYSTAL	C1	C2	R
16 MHz	30P	30P	-
24 MHz	15P	15P	-

Above table shows the reference values for crystal applications.

Note: C1, C2, R components refer to Figure A.



Typical Application Circuits, continued

### **Expanded External Data Memory and Oscillator**

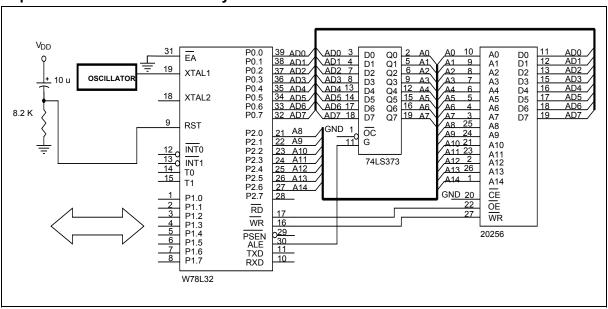
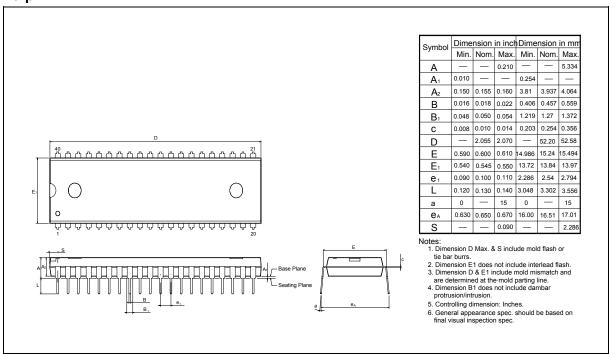


Figure B

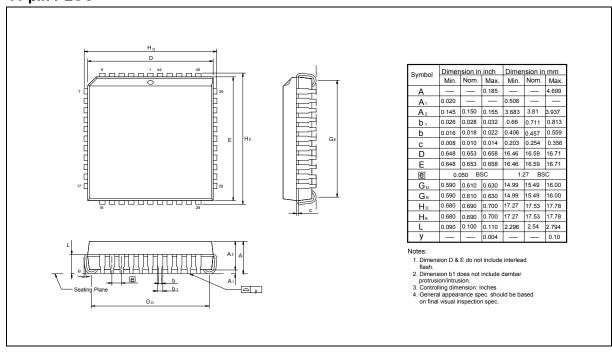


#### 12. PACKAGE DIMENSIONS

### 40-pin DIP



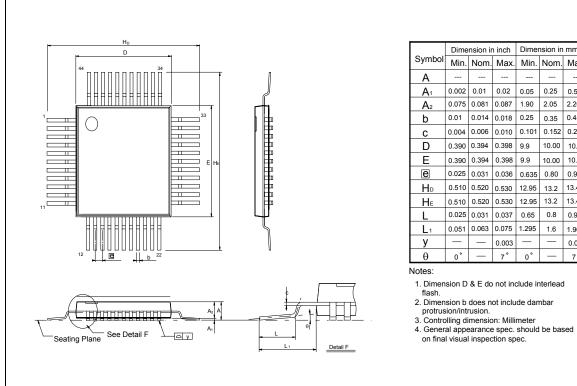
#### 44-pin PLCC





Package Dimensions, continued

## 44-pin QFP



	Dimension in inch			Dimension in mm				
Symbol	Min.	Nom.	Max.	Min.	Nom.	Max.		
Α								
<b>A</b> 1	0.002	0.01	0.02	0.05	0.25	0.5		
$A_2$	0.075	0.081	0.087	1.90	2.05	2.20		
b	0.01	0.014	0.018	0.25	0.35	0.45		
C	0.004	0.006	0.010	0.101	0.152	0.254		
D	0.390	0.394	0.398	9.9	10.00	10.1		
Е	0.390	0.394	0.398	9.9	10.00	10.1		
e	0.025	0.031	0.036	0.635	0.80	0.952		
Н□	0.510	0.520	0.530	12.95	13.2	13.45		
H≡	0.510	0.520	0.530	12.95	13.2	13.45		
L	0.025	0.031	0.037	0.65	0.8	0.95		
L₁	0.051	0.063	0.075	1.295	1.6	1.905		
у			0.003		_	0.08		
θ	o°		7°	o°	_	7°		

- 1. Dimension D & E do not include interlead flash.

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#### 13. REVISION HISTORY

VERSION	DATE	PAGE	REASONS FOR CHANGE
A2	October 2000		-
А3	April 20, 2005	16	Add Important Notice
A4	December 21, 2005	2	Add lead-free(RoHS) parts
A5	March 7, 2006	2	Add 2nd lead-free(RoHS) parts

#### **Important Notice**

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Headquarters

No. 4, Creation Rd. III, Science-Based Industrial Park, Hsinchu, Taiwan TEL: 886-3-5770066 FAX: 886-3-5665577 http://www.winbond.com.tw/

Taipei Office 9F, No.480, Rueiguang Rd., Neihu District, Taipei, 114, Taiwan, R.O.C.

TEL: 886-2-8177-7168 FAX: 886-2-8751-3579 Winbond Electronics Corporation America

2727 North First Street, San Jose,

CA 95134, U.S.A. TEL: 1-408-9436666 FAX: 1-408-5441798

Winbond Electronics Corporation Japan

7F Daini-ueno BLDG, 3-7-18 Shinyokohama Kohoku-ku, Yokohama, 222-0033 TEL: 81-45-4781881 FAX: 81-45-4781800 Winbond Electronics (Shanghai) Ltd. 27F, 2299 Yan An W. Rd. Shanghai,

200336 China TEL: 86-21-62365999 FAX: 86-21-62365998

FAX: 852-27552064

Winbond Electronics (H.K.) Ltd. Unit 9-15, 22F, Millennium City, No. 378 Kwun Tong Rd., Kowloon, Hong Kong TEL: 882-27513100

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